

FLLD261

HIGH CONDUCTANCE LOW LEAKAGE DIODE

PD350 mW @ TA = 25 Deg C BV200 V (MIN) @ IR = 5 uA

ABSOLUTE MAXIMUM RATINGS (NOTE 1)

TEMPERATURES

Storage Temperature -55 to +150 Degrees C
Operating Junction Temperature -55 to +150 Degrees C

POWER DISSIPATION (NOTES 2 & 3)

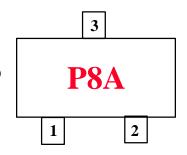
Total Device Dissipation at TA = 25 Deg C 350 mW Derating Factor per Degree C 2.8 mW

VOLTAGES & CURRENTS

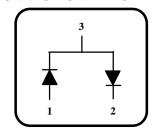
WIV Working Inverse Voltage 100 V
IO Average Rectified Current 250 mA
IF DC Forward Current 600 mA
if Recurrent Peak Forward Current 700 mA
if (surge) Peak Forward Surge Current

Pulse width = 1 second 1.0 A Pulse width = 1 microsec 3.0 A

PACKAGE TO-236AB (Low)



CONNECTION DIAGRAMS



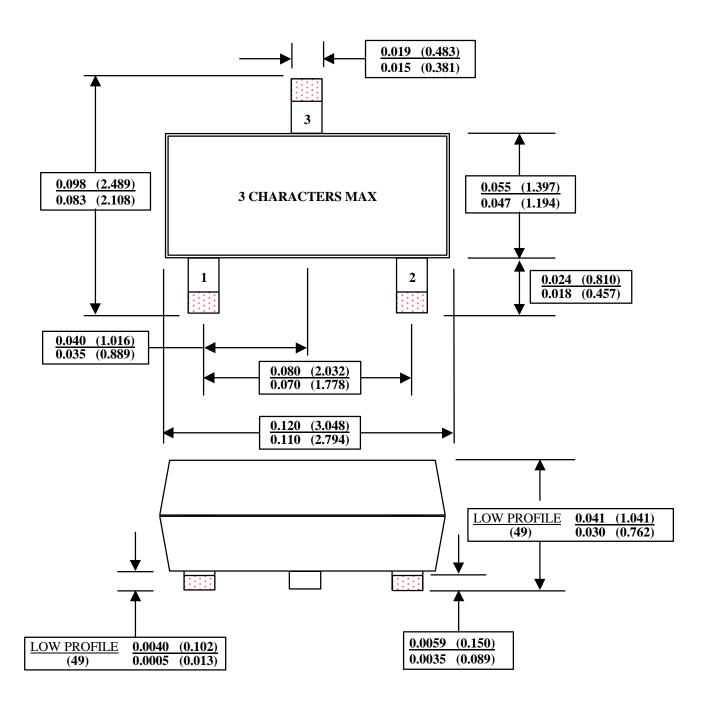
ELECTRICAL CHARACTERISTICS (25 Degrees C Ambient Temperature unless otherwise stated)

SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
SIM	CHARACTERISTICS	IVIIIN	WIAA	UNITS	TEST CONDITIONS
Bv	Breakdown Voltage	200		V	IR = 5.0 uA
IR	Reverse Voltage Leakage Current		5.0 5.0	nA uA	VR = 100 V VR = 100 V TA = 150 Deg C
V_{F}	Forward Voltage		1.40	V	IF = 200 mA
Ст	Diode Capacitance		4.0	pF	$V_R = 1.0 \ V \qquad f = 1.0 \ MHz$
Trr	Reverse Recovery Time		400	ns	$IF = IR = 50 \text{ to } 400 \text{ mA}$ $IRR = 10\% \text{ IR} \qquad RL = 100 \text{ ohms}$
TFR	Forward Recovery Time		10	ns	If = 10 mA
VFM	Peak Forward Voltage		0.9 Typ	V	IF = 10 mA Rise Time = 5 ns +/-20%

NOTES:

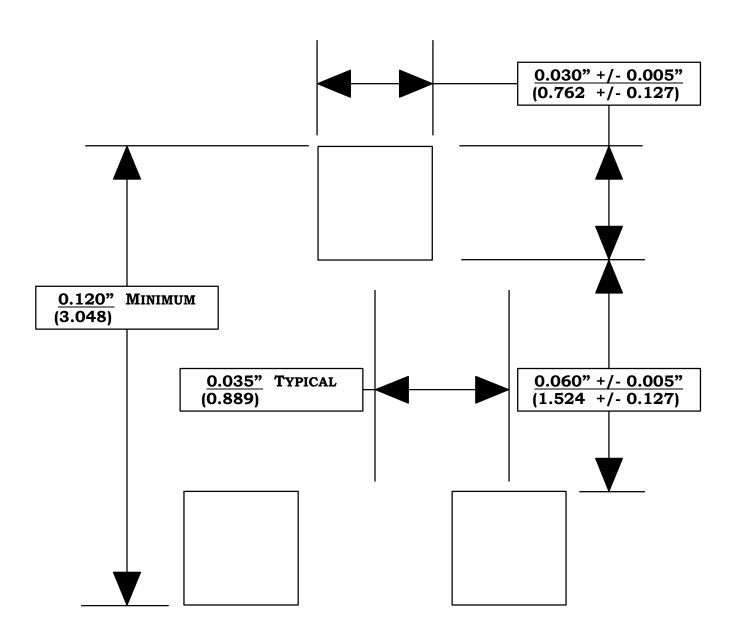
- 1. These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.
- 2. These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.





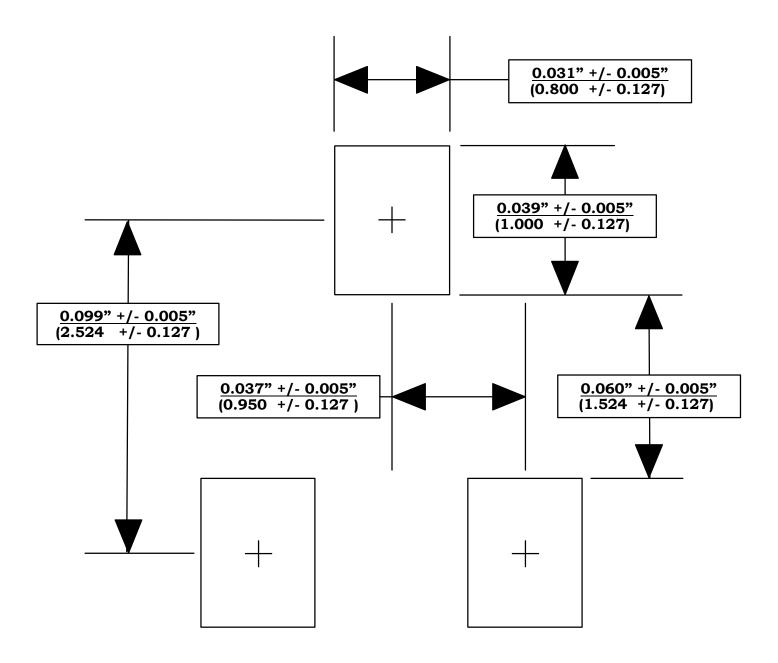






RECOMMENDED SOLDER PADS FOR SOT-23





RECOMMENDED SOLDER PADS FOR U.S., European & Japanese (SC-59) SOT-23

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